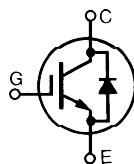


# XPT™ 650V IGBT GenX4™ w/ Diode

## IXXH30N65B4D1

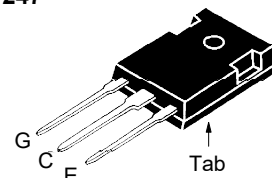
$V_{CES} = 650V$   
 $I_{C110} = 30A$   
 $V_{CE(sat)} \leq 2.0V$   
 $t_{fi(typ)} = 50ns$

Extreme Light Punch Through  
IGBT for 5-30 kHz Switching



Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ C$ to $175^\circ C$	650	V
$V_{CGR}$	$T_J = 25^\circ C$ to $175^\circ C$ , $R_{GE} = 1M\Omega$	650	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ C$ (Chip Capability)	70	A
$I_{C110}$	$T_C = 110^\circ C$	30	A
$I_{F110}$	$T_C = 110^\circ C$	40	A
$I_{CM}$	$T_C = 25^\circ C$ , 1ms	146	A
<b>SSOA</b>	$V_{GE} = 15V$ , $T_{VJ} = 150^\circ C$ , $R_G = 15\Omega$	$I_{CM} = 60$	A
<b>(RBSOA)</b>	Clamped Inductive Load	@ $V_{CE} \leq V_{CES}$	
$t_{sc}$	$V_{GE} = 15V$ , $V_{CE} = 360V$ , $T_J = 150^\circ C$	10	$\mu s$
<b>(SCSOA)</b>	$R_G = 82\Omega$ , Non Repetitive		
$P_C$	$T_C = 25^\circ C$	230	W
$T_J$		-55 ... +175	$^\circ C$
$T_{JM}$		175	$^\circ C$
$T_{stg}$		-55 ... +175	$^\circ C$
$T_L$	Maximum Lead Temperature for Soldering 1.6 mm (0.062 in.) from Case for 10s	300	$^\circ C$
$M_d$	Mounting Torque	1.13/10	Nm/lb.in.
<b>Weight</b>		6	g

### TO-247



G = Gate      C = Collector  
 E = Emitter    Tab = Collector

### Features

- Optimized for 5-30kHz Switching
- Square RBSOA
- Anti-Parallel Diode
- Short Circuit Capability
- International Standard Package

### Advantages

- High Power Density
- Extremely Rugged
- Low Gate Drive Requirement

### Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

Symbol	Test Conditions ( $T_J = 25^\circ C$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{CES}$	$I_C = 250\mu A$ , $V_{GE} = 0V$	650		V
$V_{GE(th)}$	$I_C = 250\mu A$ , $V_{CE} = V_{GE}$	4.0		6.5 V
$I_{CES}$	$V_{CE} = V_{CES}$ , $V_{GE} = 0V$ $T_J = 150^\circ C$			20 $\mu A$ 750 $\mu A$
$I_{GES}$	$V_{CE} = 0V$ , $V_{GE} = \pm 20V$			$\pm 100$ nA
$V_{CE(sat)}$	$I_C = 30A$ , $V_{GE} = 15V$ , Note 1 $T_J = 150^\circ C$	1.66 1.87		V V

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$I_C = 30\text{A}, V_{CE} = 10\text{V}$ , Note 1	25	42	S
$C_{ies}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		1460	pF
$C_{oes}$			146	pF
$C_{res}$			22	pF
$Q_{g(on)}$	$I_C = 30\text{A}, V_{GE} = 15\text{V}, V_{CE} = 0.5 \cdot V_{CES}$		52	nC
$Q_{ge}$			10	nC
$Q_{gc}$			22	nC
$t_{d(on)}$	<b>Inductive load, <math>T_J = 25^\circ\text{C}</math></b> $I_C = 30\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 400\text{V}, R_G = 15\Omega$ Note 2		20	ns
$t_{ri}$			65	ns
$E_{on}$			1.04	mJ
$t_{d(off)}$			150	ns
$t_{fi}$			50	ns
$E_{off}$			0.73	mJ
$t_{d(on)}$	<b>Inductive load, <math>T_J = 150^\circ\text{C}</math></b> $I_C = 30\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 400\text{V}, R_G = 15\Omega$ Note 2		19	ns
$t_{ri}$			46	ns
$E_{on}$			1.87	mJ
$t_{d(off)}$			146	ns
$t_{fi}$			60	ns
$E_{off}$			1.07	mJ
$R_{thJC}$				0.65 $^\circ\text{C/W}$
$R_{thCS}$		0.21		$^\circ\text{C/W}$

**Reverse Diode (FRED)**

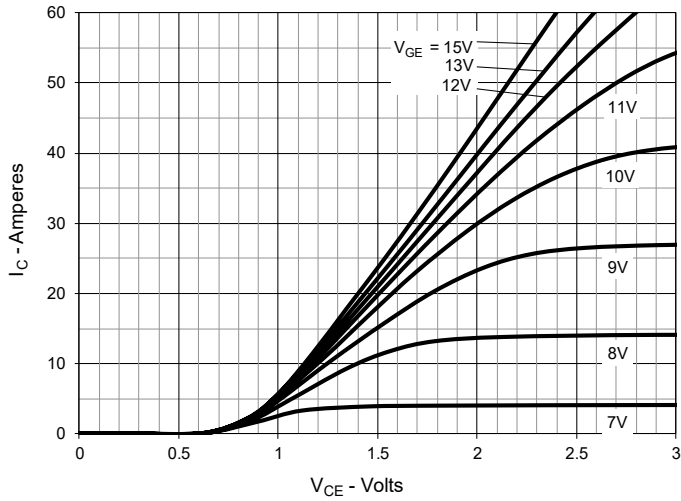
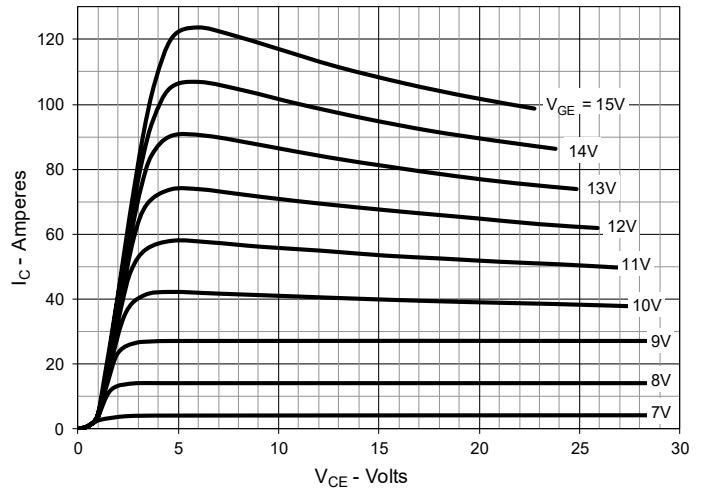
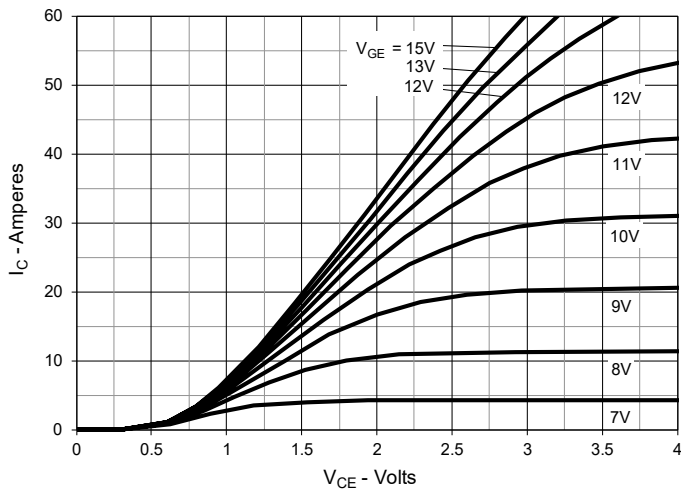
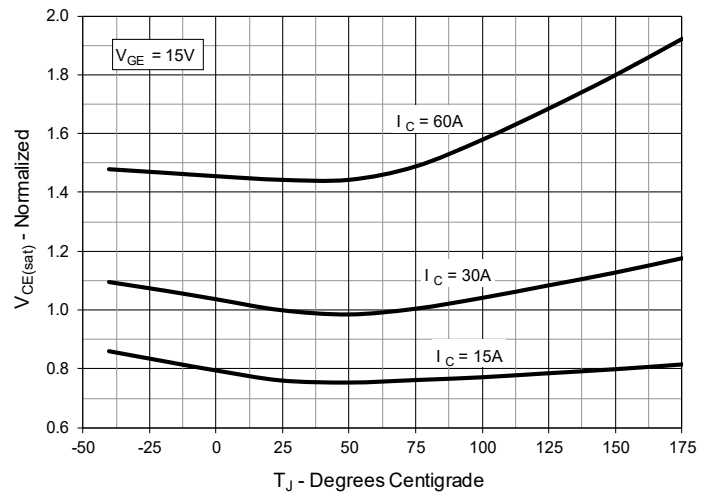
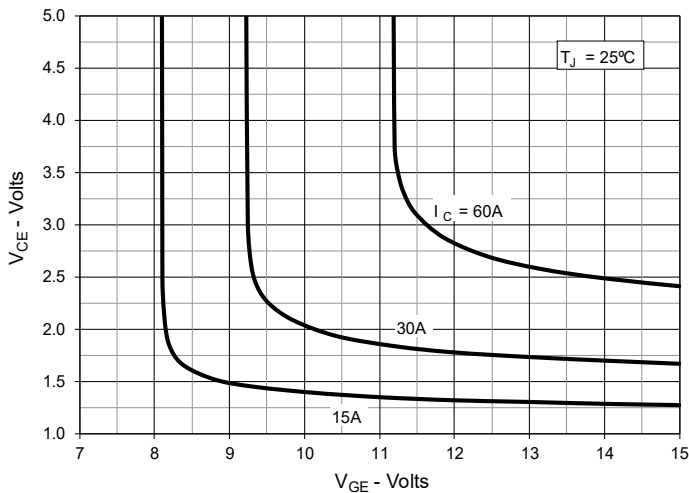
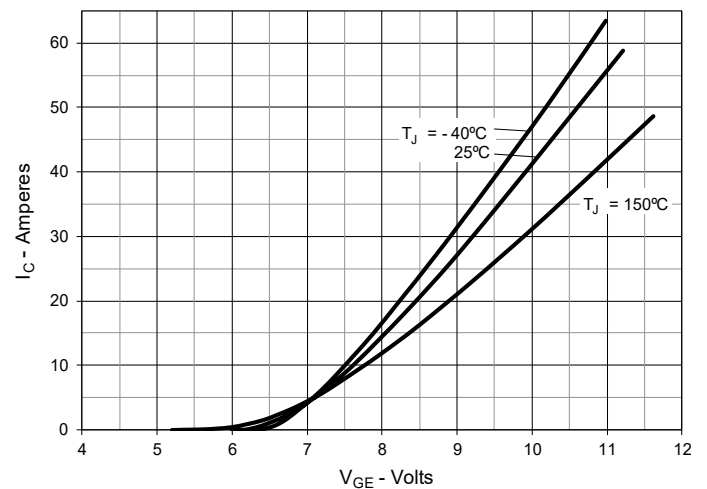
Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$V_F$	$I_F = 30\text{A}, V_{GE} = 0\text{V}$ , Note 1			2.5 V
		$T_J = 150^\circ\text{C}$	1.35	V
$I_{RM}$	$I_F = 30\text{A}, V_{GE} = 0\text{V}, -di_F/dt = 500\text{A}/\mu\text{s},$ $V_R = 400\text{V}, T_J = 150^\circ\text{C}$		14	A
$t_{rr}$			185	ns
$R_{thJC}$				0.75 $^\circ\text{C/W}$

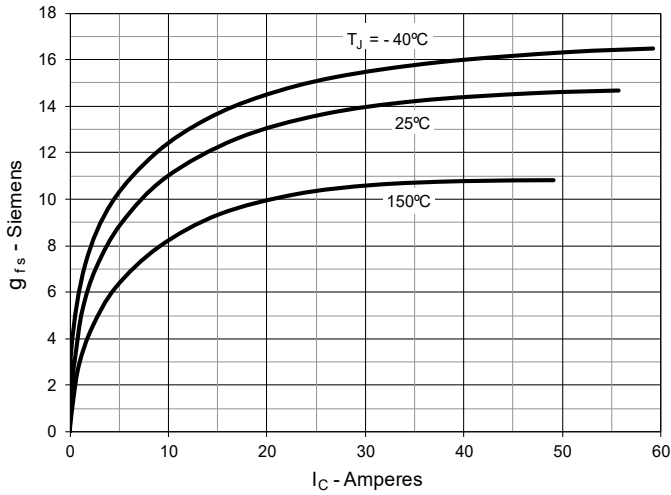
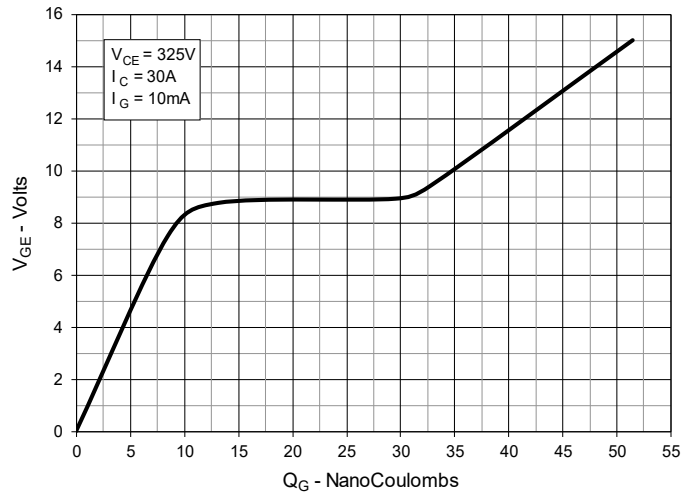
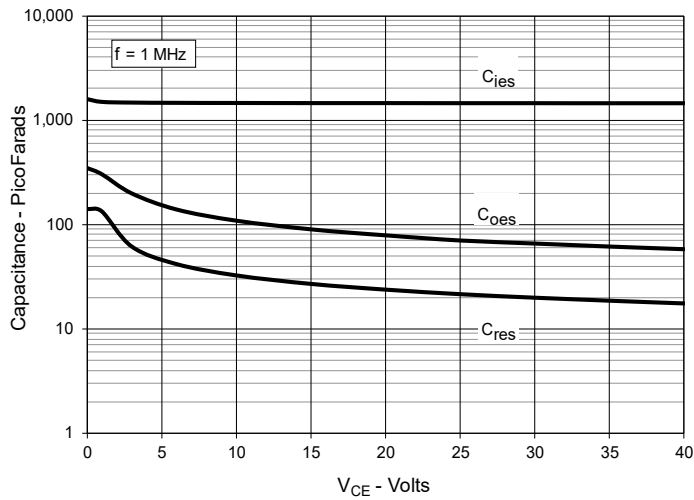
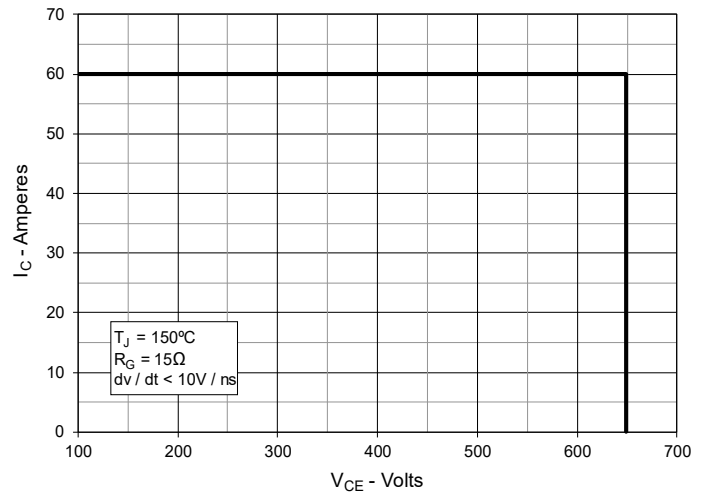
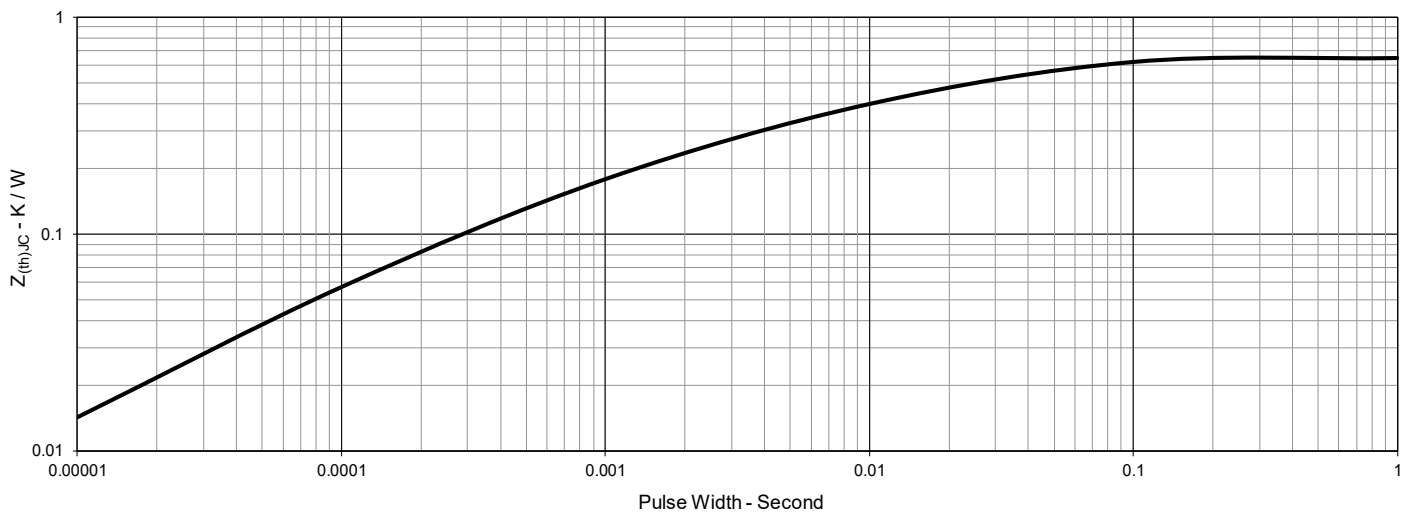
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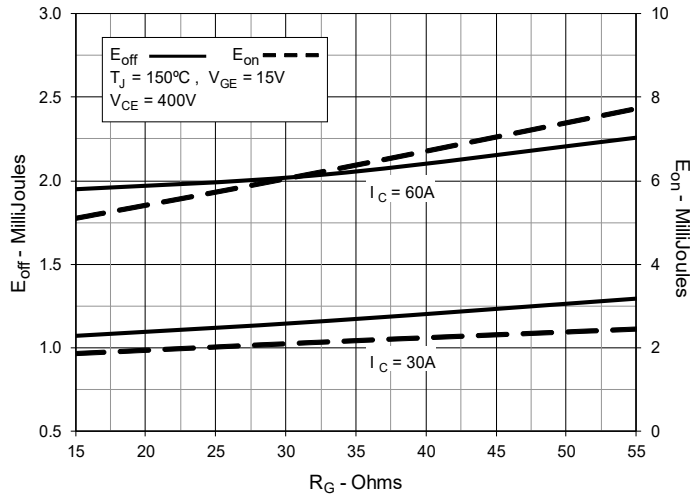
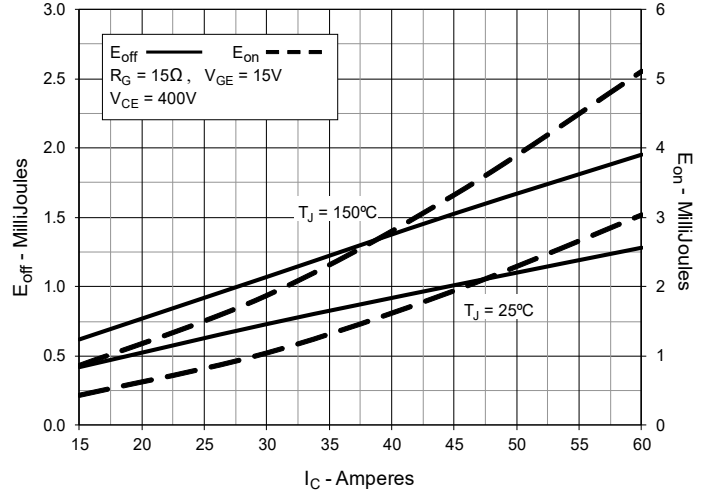
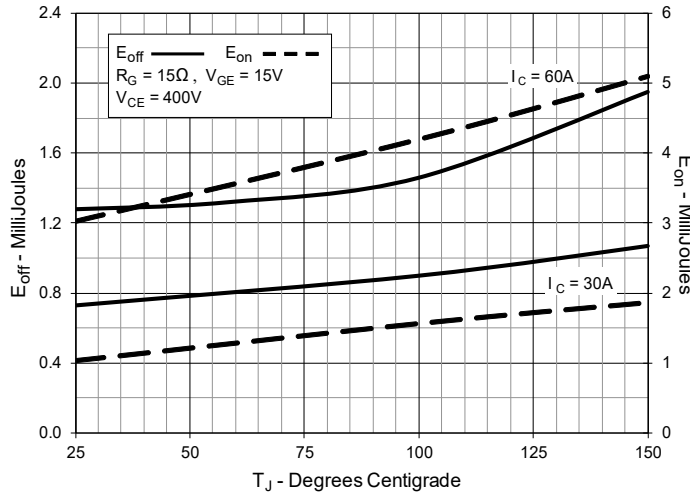
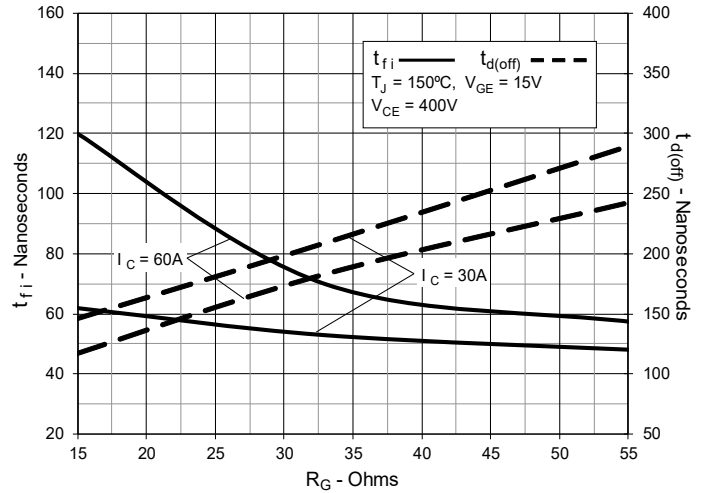
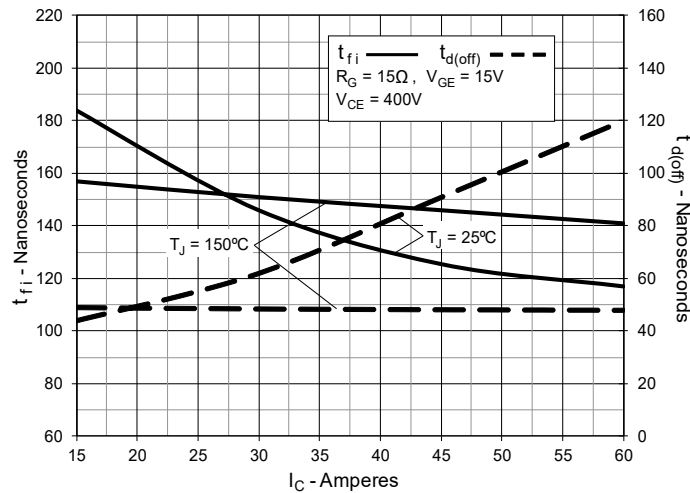
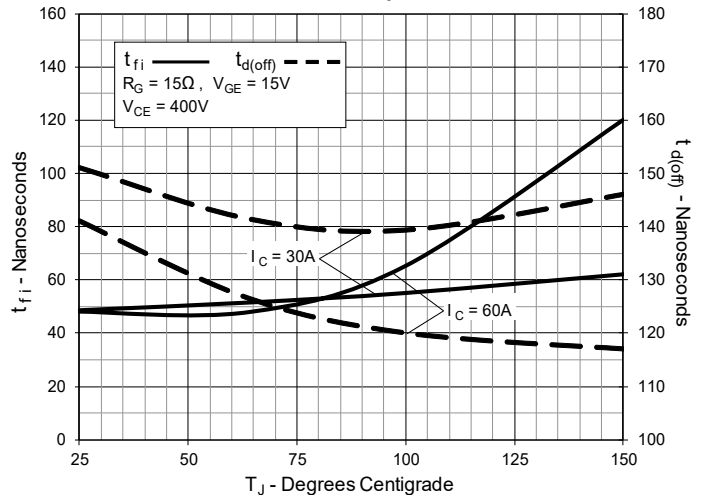
1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .
2. Switching times & energy losses may increase for higher  $V_{CE}$ (clamp),  $T_J$  or  $R_G$ .

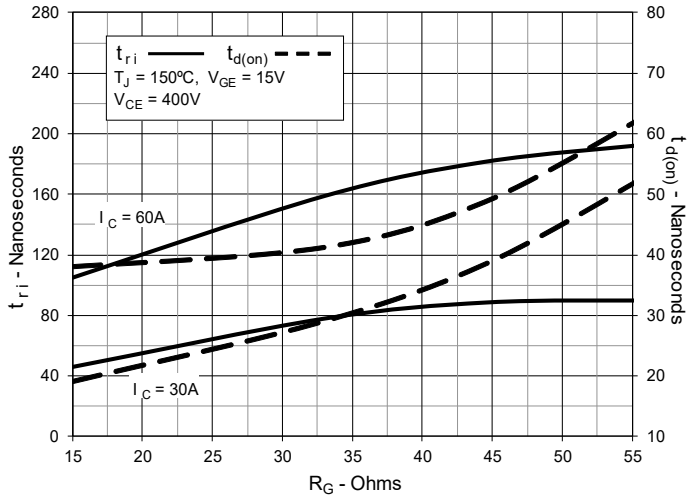
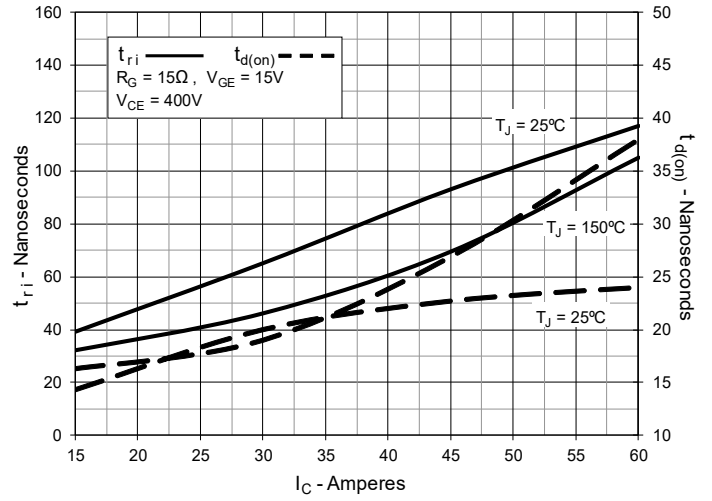
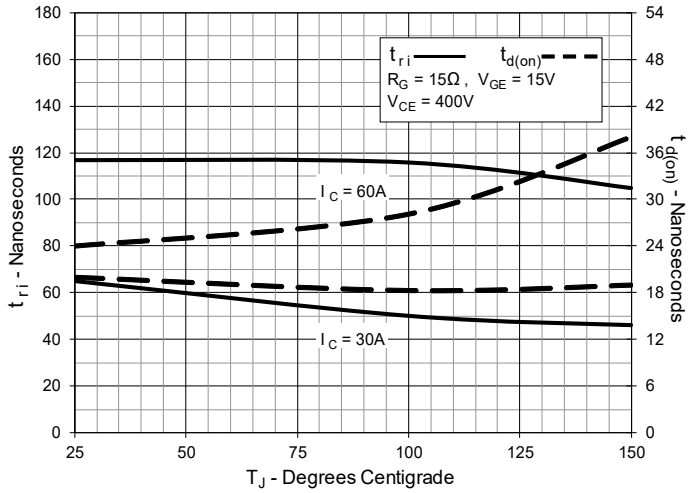
Littelfuse reserves the right to change limits, test conditions, and dimensions.

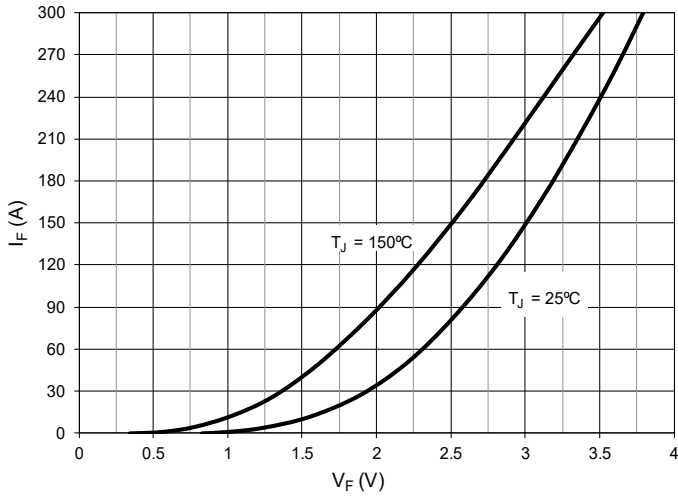
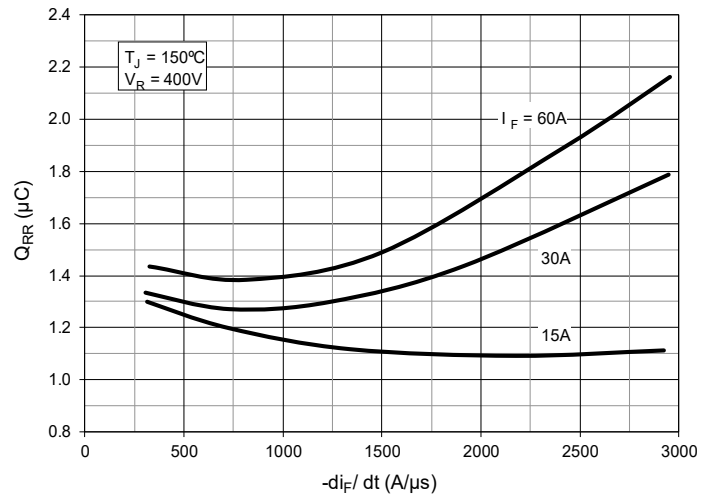
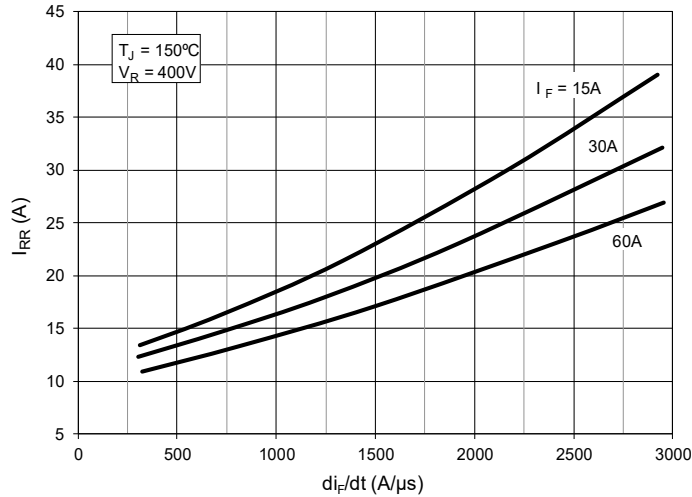
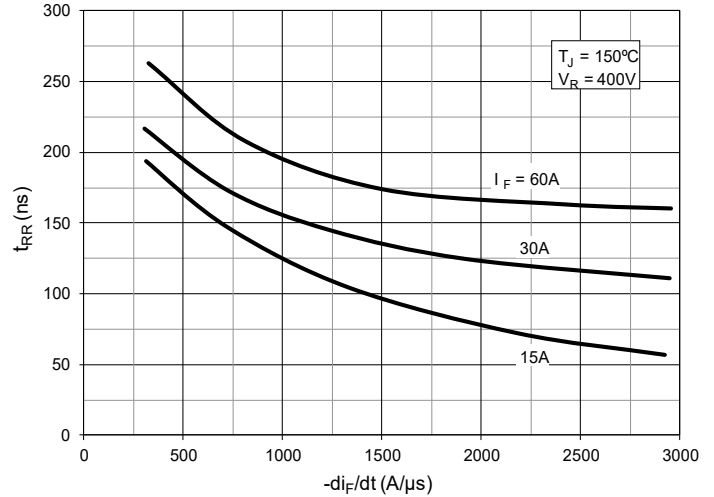
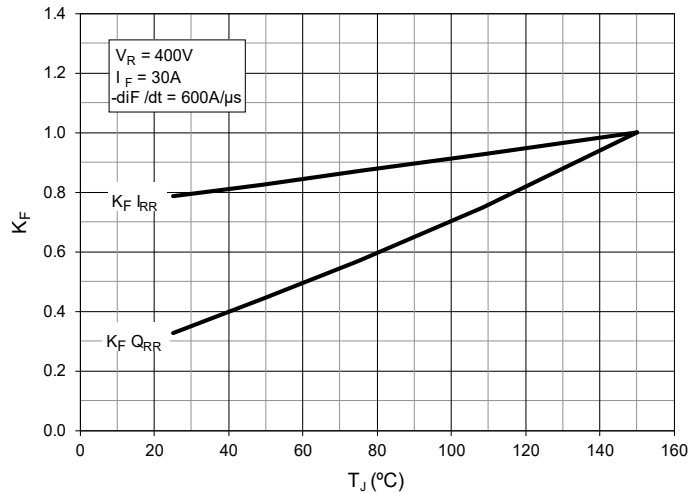
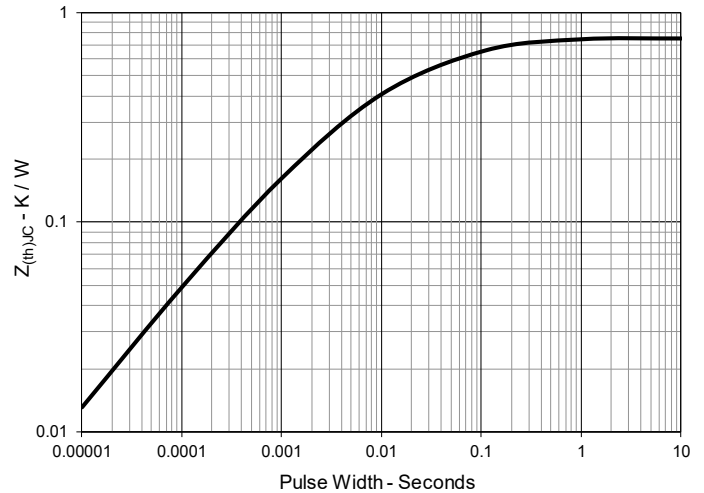
IXYS MOSFETs and IGBTs are covered 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2  
by one or more of the following U.S. patents: 4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2  
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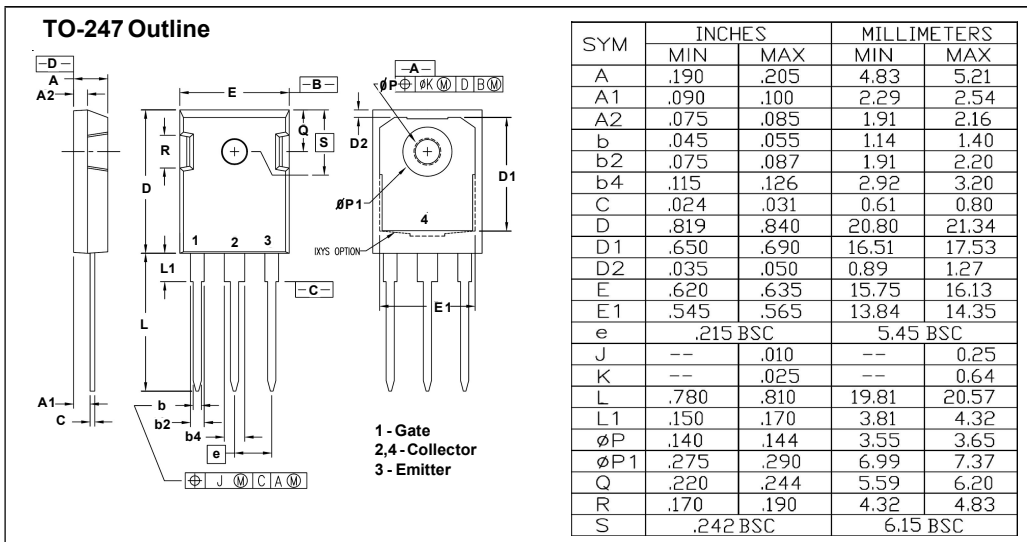
**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$** 

**Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$** 

**Fig. 3. Output Characteristics @  $T_J = 150^\circ\text{C}$** 

**Fig. 4. Dependence of  $V_{CE(sat)}$  on Junction Temperature**

**Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage**

**Fig. 6. Input Admittance**


**Fig. 7. Transconductance**

**Fig. 8. Gate Charge**

**Fig. 9. Capacitance**

**Fig. 10. Reverse-Bias Safe Operating Area**

**Fig. 11. Maximum Transient Thermal Impedance (IGBT)**


**Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance**

**Fig. 13. Inductive Switching Energy Loss vs. Collector Current**

**Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature**

**Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance**

**Fig. 16. Inductive Turn-off Switching Times vs. Collector Current**

**Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature**


**Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance**

**Fig. 19. Inductive Turn-on Switching Times vs. Collector Current**

**Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature**


**Fig. 21. Diode Forward Characteristics**

**Fig. 22. Reverse Recovery Charge vs.  $-di_F/dt$** 

**Fig. 23. Reverse Recovery Current vs.  $-di_F/dt$** 

**Fig. 24. Reverse Recovery Time vs.  $-di_F/dt$** 

**Fig. 25. Dynamic Parameters  $Q_{RR}$ ,  $I_{RR}$  vs. Junction Temperature**

**Fig. 26. Maximum Transient Thermal Impedance (Diode)**








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